



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

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01

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 104 FR4 35 L50.35 P10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_104\_FR4\_35\_L50.35\_p10

| Layers          | in $\mu$  | Material | Build-Up                       | Assembly |
|-----------------|-----------|----------|--------------------------------|----------|
| <b>Layer-1</b>  | 35 $\mu$  | Copper   |                                | A1 B     |
|                 | 100 $\mu$ | Prepreg  | (100 $\mu$ PrePreg-Type: 2125) |          |
|                 | 100 $\mu$ | Prepreg  |                                |          |
| <b>Layer-2</b>  | 35 $\mu$  | Copper   |                                |          |
|                 | 500 $\mu$ | L-FR4    |                                |          |
| <b>Layer-3</b>  | 35 $\mu$  | Copper   |                                |          |
|                 | 100 $\mu$ | Prepreg  |                                |          |
|                 | 100 $\mu$ | Prepreg  |                                |          |
| <b>Layer-99</b> | 35 $\mu$  | Copper   |                                |          |

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